Xperi Partners With UMC to Support Production of Direct and Hybrid Bonding 3D Semiconductor Technologies

Partnership enables UMC to develop and manufacture products utilizing Invensas DBI and ZiBond technologies

SAN JOSE, Calif.--(BUSINESS WIRE)-- Xperi Corporation (Nasdaq:XPER) ("Xperi") is pleased to announce a partnership with leading global semiconductor foundry, UMC. This strategic partnership will enable the companies to support the growing demand for Invensas ZiBond® and Invensas DBI® 3D semiconductor technologies.

Together, Xperi and UMC will further optimize and commercialize the ZiBond and DBI technologies for a wide range of semiconductor devices including image sensors, radio frequency (RF), MEMS, display drivers, touch controllers, SoC, analog, power and mixed-signal devices. Wafer to wafer (W2W) and die to wafer (D2W) bonding and 3D interconnect implementations will be employed to address the requirements of a variety of applications within the mobile, consumer, automotive, communication, industrial and Internet of Things (IoT) industries.

"As a world-leading semiconductor foundry, we are committed to delivering leading-edge solutions to our customers," said Wenchi Ting, vice president of specialty technologies at UMC. "By partnering with Xperi and the Invensas team, true pioneers in direct and hybrid bonding technologies, we continue to be well-positioned to meet our customers' evolving requirements for advanced wafer bonding technologies."

"We are excited to join forces with UMC, a premier global foundry engaged in every major sector of the electronics industry, to expand the production base for our ZiBond and DBI bonding and 3D interconnect platforms," said Craig Mitchell, president, Invensas. "We look forward to working together to proliferate these enabling technologies into a wide range of high volume semiconductor applications."

ZiBond is a low temperature homogenous direct bonding technology that forms strong bonds between semiconductor wafers or die with same or different coefficients of thermal expansion. This technology is used in image sensors, MEMS and various RF front-end devices.

DBI is a low temperature hybrid direct bonding technology that allows semiconductor wafers or die to be bonded with exceptionally fine pitch 3D electrical interconnect. This technology is suited for various semiconductor devices such as image sensors, DRAM, MEMS and RF devices.

Products employing these technologies are found in smartphones, tablets, laptops, cameras, televisions and gaming consoles, as well as in industrial, automotive and IoT electronic devices.

For more information about Xperi and its technologies platforms, please visit www.xperi.com.

About Xperi Corporation

Xperi Corporation (Nasdaq: XPER) and its brands, DTS, FotoNation, HD Radio, Invensas and Tessera, are dedicated to creating innovative technology solutions that enable extraordinary experiences for people around the world. Xperi's solutions are licensed by hundreds of leading global partners and have shipped in billions of products in areas including premium audio, automotive, broadcast, computational imaging, computer vision, mobile computing and communications, memory, data storage, and 3D semiconductor interconnect and packaging. For more information, please call 408-321-6000 or visit www.xperi.com.

About UMC

UMC (NYSE: UMC, TWSE: 2303) is a leading global semiconductor foundry that provides advanced IC production for applications spanning every major sector of the electronics industry. UMC's comprehensive foundry solutions enable chip designers to leverage the company's sophisticated technology and manufacturing, which include world-class 28nm High-K/Metal Gate technology, 14nm FinFET volume production, specialty process platforms specifically developed for AI, 5G and IoT applications and the automotive industry's highest-rated AEC-Q100 Grade-0 manufacturing capabilities for the production of ICs found in vehicles. UMC's 11 wafer fabs are strategically located throughout Asia and are able to produce over 600,000 wafers per month. The company employs more than 20,000 people worldwide, with offices in Taiwan, China, Europe, Japan, Korea, Singapore, and the United States. UMC can be found on the web at http://www.umc.com.

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